

## Lonten N-channel 500V, 17A Power MOSFET

### Description

The Power MOSFET is fabricated using the advanced planer **VDMOS** technology. The resulting device has low conduction resistance, superior switching performance and high avalanche energy.

### Features

- ◆ Low  $R_{DS(on)}$
- ◆ Low gate charge (typ.  $Q_g = 50.7 \text{ nC}$ )
- ◆ 100% UIS tested
- ◆ RoHS compliant

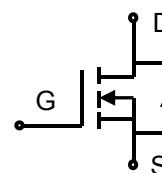
### Applications

- ◆ Power factor correction.
- ◆ Switched mode power supplies.
- ◆ LED driver.

### Product Summary

$V_{DSS}$	500V
$I_D$	17A
$R_{DS(on),max}$	0.33Ω
$Q_{g,typ}$	50.7 nC

### Pin Configuration


**TO-220F**

**N-Channel MOSFET**

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	500	V
Continuous drain current ( $T_C = 25^\circ\text{C}$ )	$I_D$	17	A
( $T_C = 100^\circ\text{C}$ )		9	A
Pulsed drain current <sup>1)</sup>	$I_{DM}$	68	A
Gate-Source voltage	$V_{GSS}$	$\pm 30$	V
Avalanche energy, single pulse <sup>2)</sup>	$E_{AS}$	1037	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	36.7	W
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150	°C
Continuous diode forward current	$I_S$	17	A
Diode pulse current	$I_{S,pulse}$	68	A

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, Junction-to-case	$R_{\theta JC}$	3.4	°C/W
Thermal resistance, Junction-to-ambient <sup>3)</sup>	$R_{\theta JA}$	65	°C/W

### Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube
LND17N50	TO-220F	LND17N50	50

**Electrical Characteristics**
 $T_c = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=0.25 \text{ mA}$	500	-	-	V
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=0.25 \text{ mA}$	2	-	4	V
Drain cut-off current	$I_{\text{DSS}}$	$V_{\text{DS}}=500 \text{ V}, V_{\text{GS}}=0 \text{ V},$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	-	-	1 100	$\mu\text{A}$
Gate leakage current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}}=30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	100	nA
Gate leakage current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}}=-30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=8.5 \text{ A}, T_j=25^\circ\text{C}$	-	0.26	0.33	$\Omega$
Gate resistance	$R_g$	$V_{\text{GS}}=0 \text{ V}, V_{\text{DS}}=0 \text{ V}, f=1 \text{ MHz}$	-	1.2	-	$\Omega$
<b>Dynamic characteristics</b>						
Input capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25 \text{ V}, V_{\text{GS}} = 0 \text{ V},$ $f = 1 \text{ MHz}$	-	2655	-	pF
Output capacitance	$C_{\text{oss}}$		-	251	-	
Reverse transfer capacitance	$C_{\text{rss}}$		-	1.9	-	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 250 \text{ V}, I_{\text{D}} = 17 \text{ A}$ $R_G = 10 \Omega, V_{\text{GS}} = 15 \text{ V}$	-	14.5	-	ns
Rise time	$t_r$		-	39.6	-	
Turn-off delay time	$t_{\text{d(off)}}$		-	89	-	
Fall time	$t_f$		-	11	-	
<b>Gate charge characteristics</b>						
Gate to source charge	$Q_{\text{gs}}$	$V_{\text{DD}}=400 \text{ V}, I_{\text{D}}=17 \text{ A},$ $V_{\text{GS}}=0 \text{ to } 10 \text{ V}$	-	12.6	-	nC
Gate to drain charge	$Q_{\text{gd}}$		-	18	-	
Gate charge total	$Q_g$		-	50.7	-	
Gate plateau voltage	$V_{\text{plateau}}$		-	5	-	V
<b>Reverse diode characteristics</b>						
Diode forward voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0 \text{ V}, I_{\text{F}}=17 \text{ A}$	-	-	1.5	V
Reverse recovery time	$t_{\text{rr}}$	$V_R=400 \text{ V}, I_F=17 \text{ A},$ $dI_F/dt=100 \text{ A}/\mu\text{s}$	-	366	-	ns
Reverse recovery charge	$Q_{\text{rr}}$		-	4212	-	$\mu\text{C}$
Peak reverse recovery current	$I_{\text{rrm}}$		-	23	-	A

**Notes:**

1. Pulse width limited by maximum junction temperature.
2.  $V_{\text{DD}}=60 \text{ V}, L=10 \text{ mH}, I_{\text{AS}} = 14.4 \text{ A}$ , Starting  $T_j = 25^\circ\text{C}$ .
- 3: The value of  $R_{\text{thJA}}$  is measured by placing the device in a still air box which is one cubic foot.

## Electrical Characteristics Diagrams

Figure 1. Typical Output Characteristics

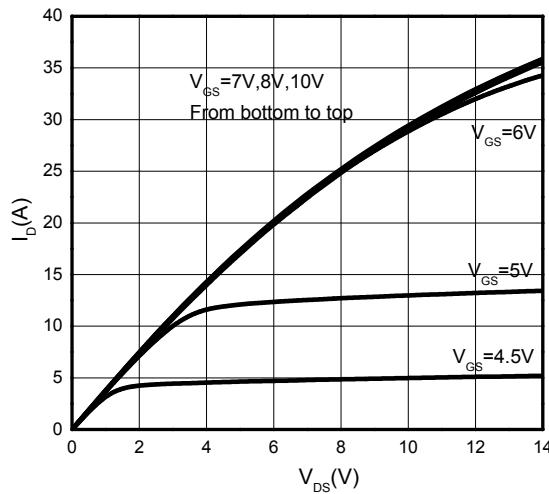


Figure 2. Transfer Characteristics

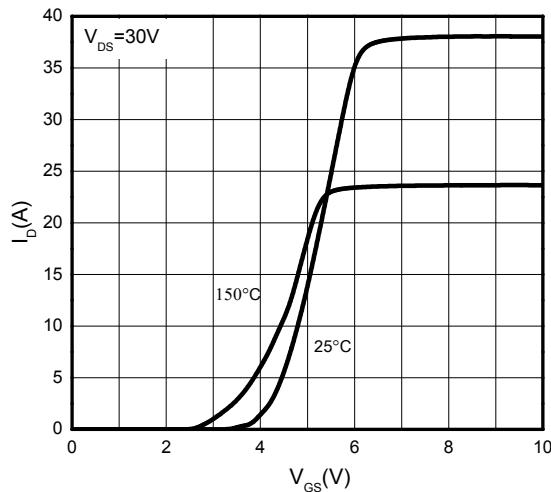


Figure 3. On-Resistance vs. Drain Current

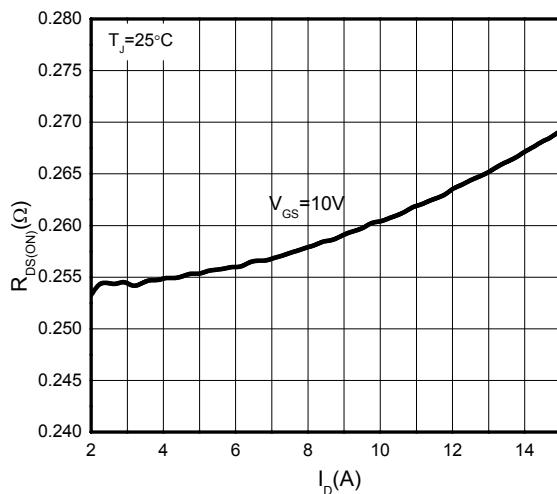


Figure 4. On-Resistance vs. Temperature

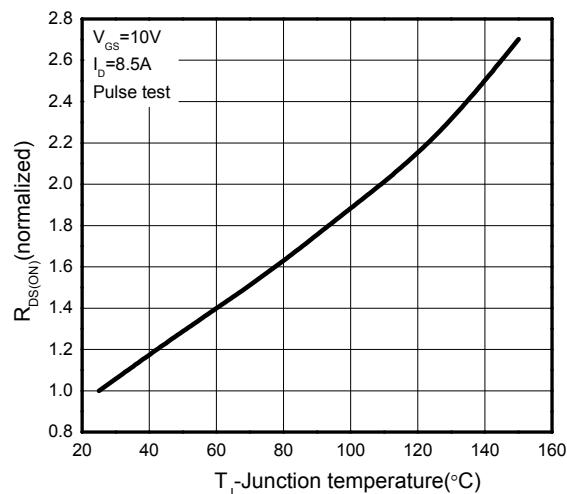


Figure 5. Breakdown Voltage vs. Temperature

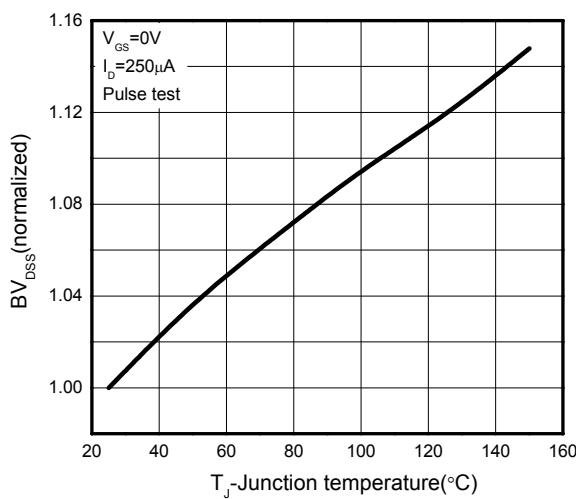


Figure 6. Threshold Voltage vs. Temperature

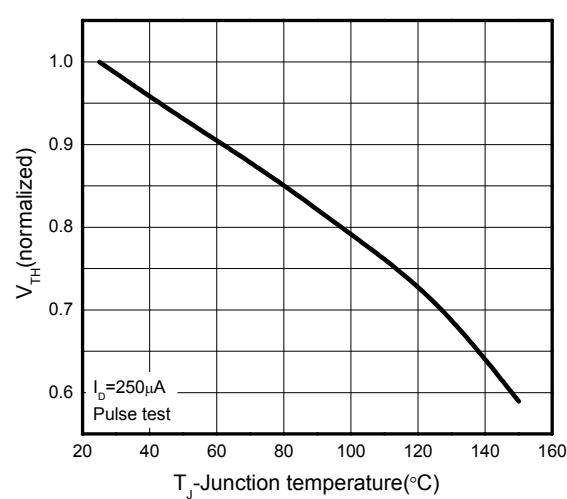


Figure 7.Rds(on) vs. Gate Voltage

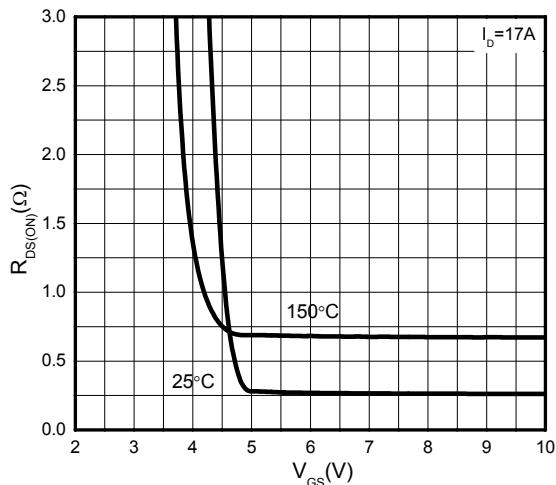


Figure 8.Body-Diode Characteristics

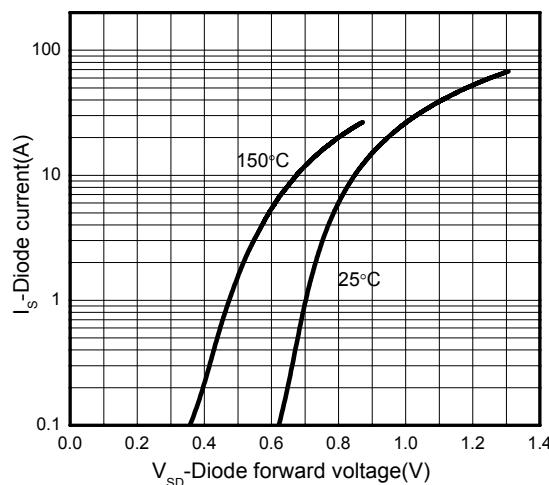


Figure 9. Capacitance Characteristics

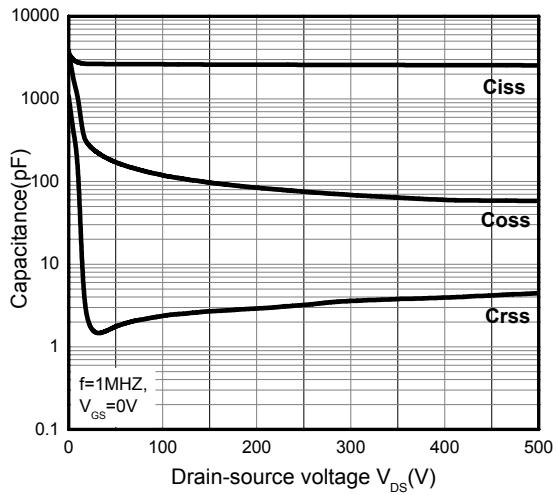


Figure 11. Continuous Drain Current vs. Temperature

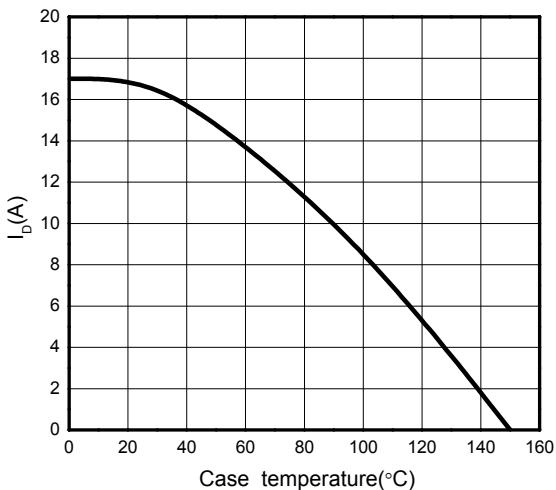


Figure 10. Gate Charge Characteristics

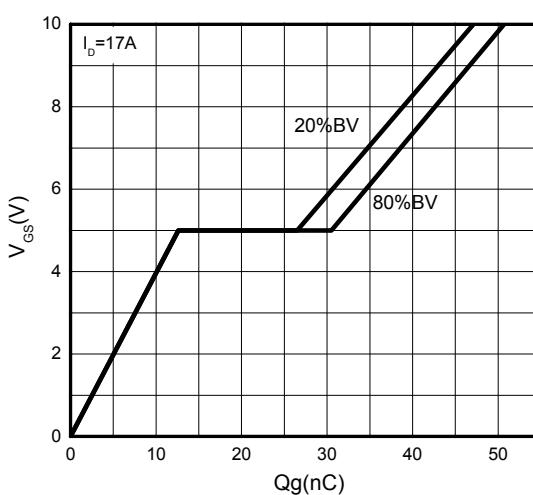


Figure 12. Power Dissipation vs. Temperature

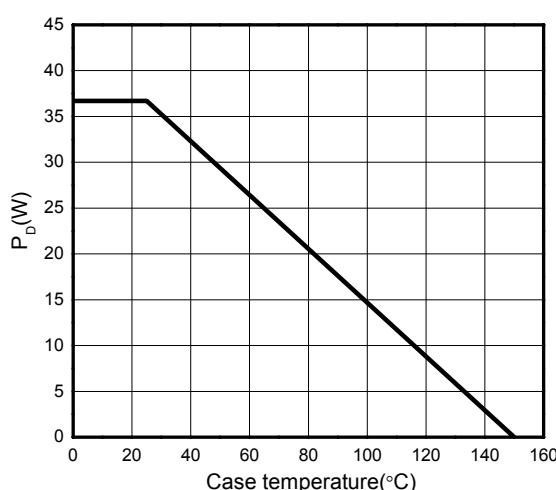


Figure 13: Safe Operating Area

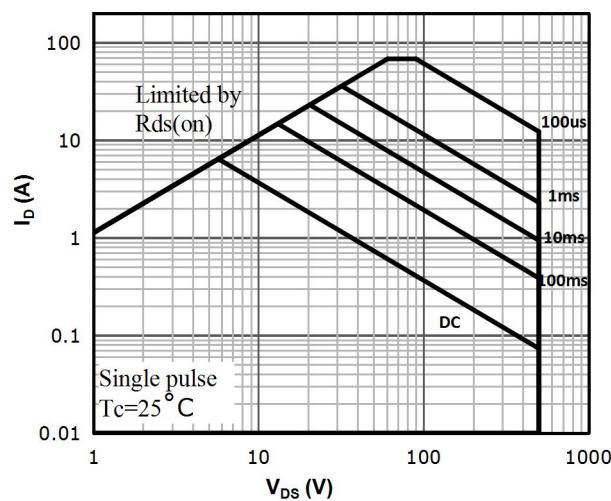
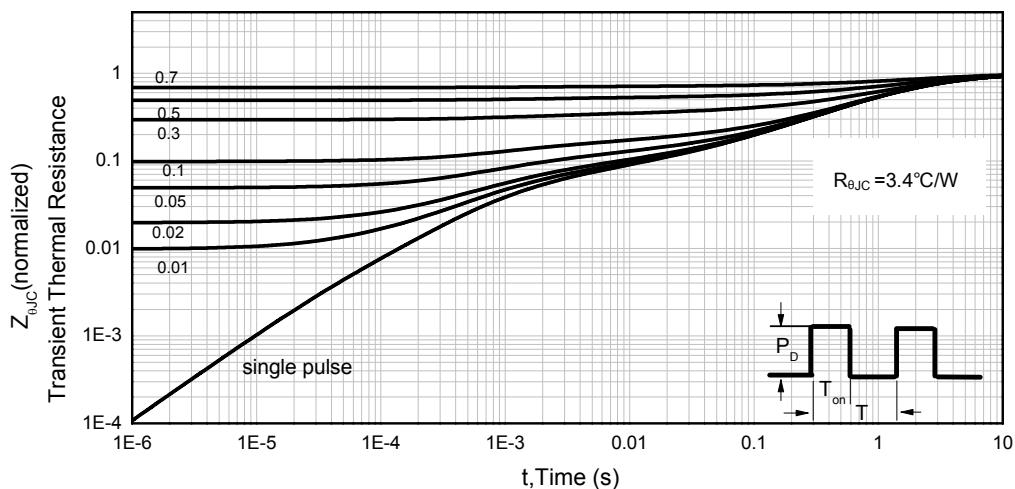
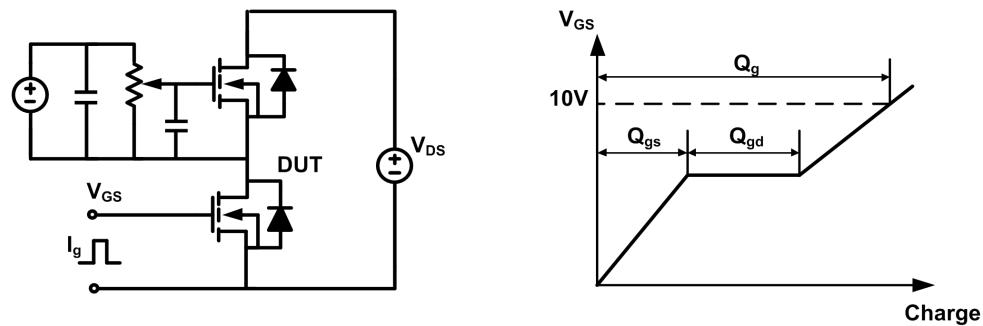


Figure 14. Transient Thermal Impedance, Junction to Case

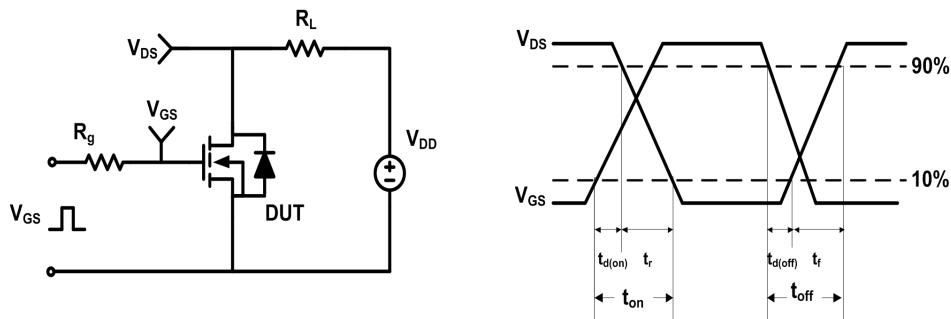


## Test Circuit & Waveforms

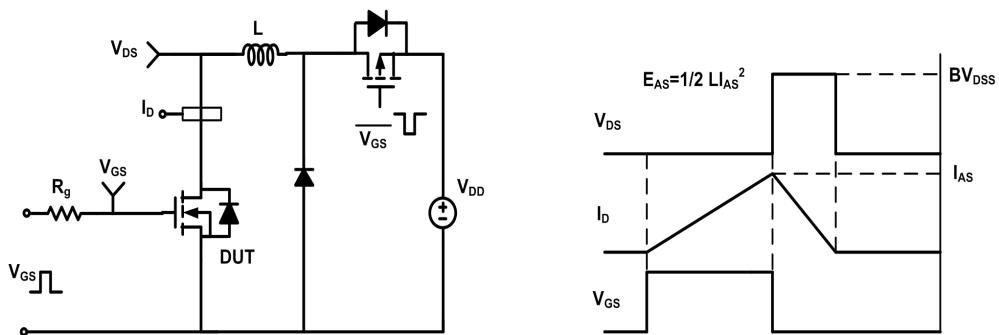
Gate Charge Test Circuit & Waveform



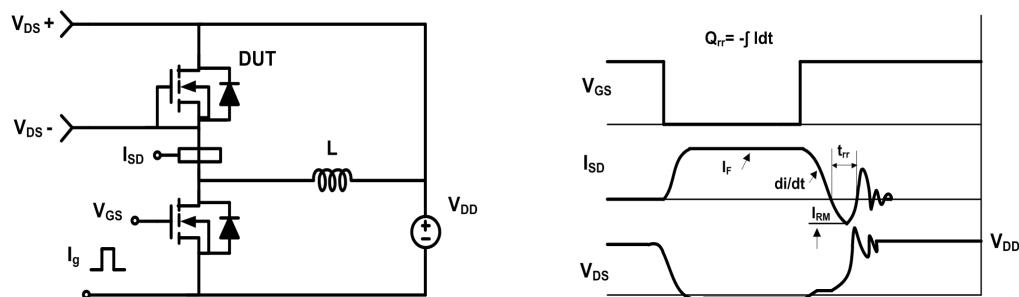
Resistive Switching Test Circuit & Waveform



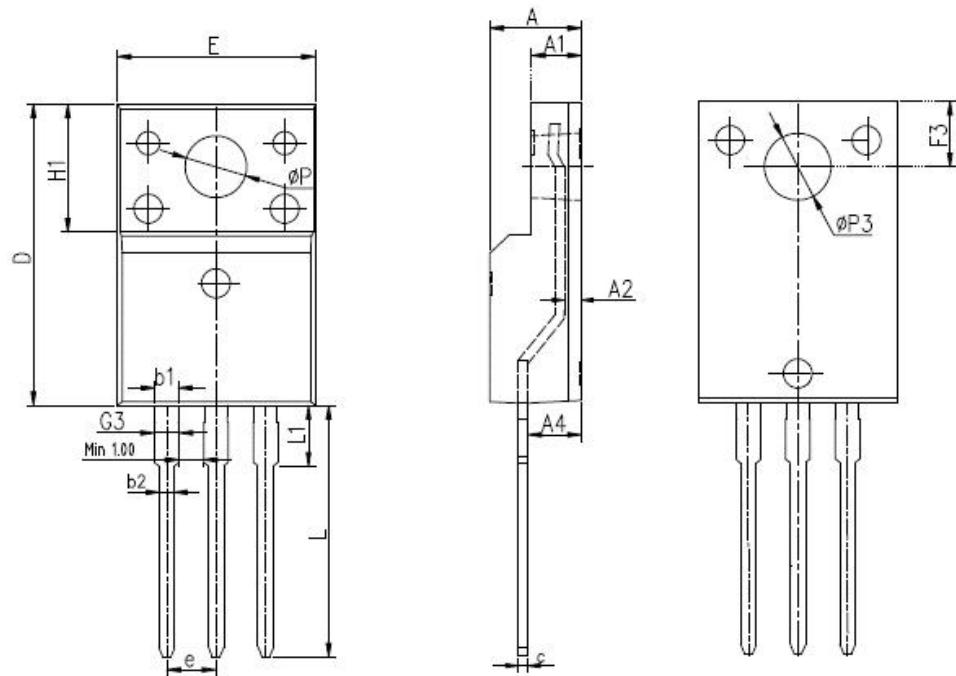
Unclamped Inductive Switching (UIS) Test Circuit & Waveform



Diode Recovery Test Circuit & Waveform



### Mechanical Dimensions for TO-220F



DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES	
SYMBOL	MIN	MAX	MIN	MAX
A	4.4	4.9	0.173	0.193
A1	2.34	2.74	0.092	0.108
A2	0.3	0.7	0.012	0.028
A4	2.5	2.96	0.098	0.117
c	0.4	0.7	0.016	0.028
D	15.57	16.4	0.613	0.646
E	9.96	10.4	0.392	0.409
H1	6.48	6.95	0.255	0.274
e	2.54BSC		0.1BSC	
L	12.64	14.2	0.498	0.559
L1	2.88	3.6	0.113	0.142
ΦP	3	3.38	0.118	0.133
ΦP3	3.15	3.65	0.124	0.144
F3	3.15	3.45	0.124	0.136
G3	1.15	1.58	0.045	0.062
b1	1.18	1.43	0.046	0.056
b2	0.7	1	0.028	0.039

## Version Information

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LND17N50

Revision:2020-11-16 ,Rev 0.1

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